

IR Communication Device Lead-free replacement list October 2005

\*These models in this list show the common and widely-distributed products as the leaded type.

If you can not find out the model you are looking for, or not know the current production status of lead-free models.

Leaded part No.	Lead-free availability	Lead-free part No.	Outline	Solder Material	Soldering Condition
GL710	Yes	GL710J00000F	Single-ended lead	Sn-Ag-Cu	See appendix
GP2W0004XP	Yes	GP2W0004XP0F	Leadless package	Sn-Cu	See appendix
GP2W0004YP	Yes	GP2W0004YP0F	Leadless package	Sn-Cu	See appendix
-	Yes	GP2W0110VY	J-leaded package	Pd(Au flash )	See appendix
GP2W0110YPS	Yes	GP2W0110YPSF	Leadless package	Sn-Cu	See appendix
GP2W0112YP	Yes	GP2W0112YP0F	Leadless package	Sn-Cu	See appendix
GP2W0114YPS	Yes	GP2W0114YP0F	Leadless package	Sn-Cu	See appendix
GP2W0116YPS	Yes	GP2W0116YP0F	Leadless package	Sn-Cu	See appendix
GP2W0118YPS	Yes	GP2W0118YP0F	Leadless package	Sn-Cu	See appendix
GP2W1001YP	Yes	GP2W1001YP0F	Leadless package	Sn-Cu	See appendix
GP2W1002YP	Yes	GP2W1002YP0F	Leadless package	Sn-Cu	See appendix
GP2W1301YP	Yes	GP2W1301YP0F	Leadless package	Sn-Cu	See appendix
-	Yes	GP2W1302YP	Leadless package	Sn-Cu	See appendix
-	Yes	GP2W1304YP	Leadless package	Sn-Cu	See appendix
-	Yes	GP2W3250YP	Leadless package	Sn-Cu	See appendix

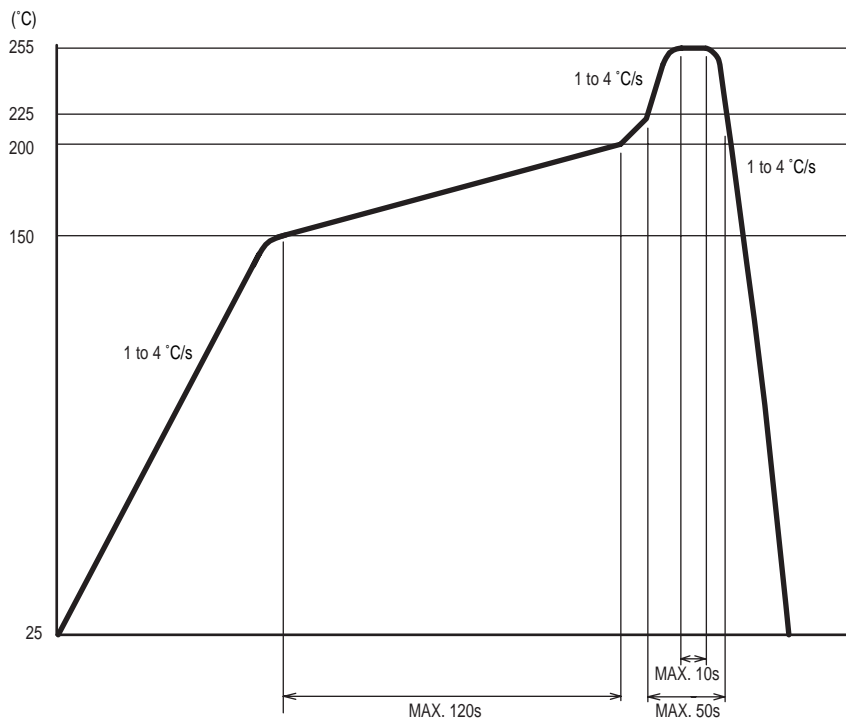
## ■ IR Data Communication Device : Lead-free part soldering conditions Leadless package

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### ● Reflow Soldering

Reflow soldering should follow the temperature profile shown below.  
Soldering should not exceed the curve of temperature profile and time.  
Please don't solder more than twice.

Reflow interval shall be within two days under conditions, 10 to 30°C, 70%RH or less.



An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin.

So keep the package temperature within that specified in above.

Also avoid immersing the resin part in the solder.

Even if within the temperature profile above, there is the possibility that the gold wire in package is broken in case that the deformation of PWB gives the affection to lead pins.  
Please use after confirmation the conditions fully by actual solder reflow machine.

### ● Hand Soldering

- Soldering iron should be less than 25W, and temperature of point of soldering iron should be less than 300°C.
- Soldering time should be within 5s one time only.
- Soldered product should be treated after it cooled down to normal temperature.

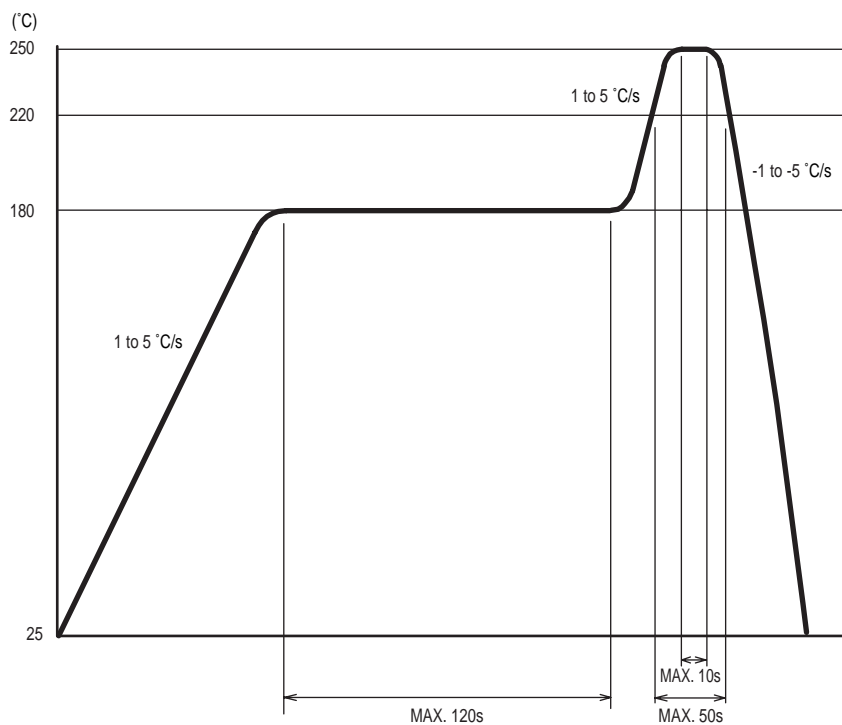
## ■ IR Data Communication Device : Lead-free part soldering conditions J-leaded package

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### ● Reflow Soldering

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An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin.

So keep the package temperature within that specified in above.

Also avoid immersing the resin part in the solder.

Even if within the temperature profile above, there is the possibility that the gold wire in package is broken in case that the deformation of PWB gives the affection to lead pins.  
Please use after confirmation the conditions fully by actual solder reflow machine.

### ● Hand Soldering

- Hand soldering should be completed below 380°C and within 5s.
- Please solder one time only.
- Soldered product should be treated after it cooled down to normal temperature.

## ■ IR Data Communication Device : Lead-free part soldering conditions Single ended lead package (IR Emitting Diode)

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### ● Soldering method

- Soldering should be completed below 260°C and within 3s .
- Soldering area should be 1.6 mm or more away from the edge of resin package.
- Please take care not to let any external stress imposed on to lead pins.
- Please don't do soldering at preheated condition. Please don't solder by reflow.

### ● Other notices

- Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.